

# Product Change Notification - JAON-080JZL283

**Date:** 25 May 2016

**Product Category:** Analog (Linear & Mixed Signal) AND Interface; SMSC; 8-bit Microcontrollers; 16-bit Microcontrollers and Digital Signal Controllers; RF and Security; Touch Sensing Technologies; Analog (Thermal, Power Management & Safety)

**Notification subject:** CCB 1834 Final Notice: Qualification of CuPdAu wire in selected products of the 40K, 57K, 77K, 90K, 120K, 150K, 160K, 0.25um TSMC, 200K and X-fab wafer technologies available in PDIP packages in MMT.

**Notification text:** **PCN Status:**  
Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 40K, 57K, 77K, 90K, 120K, 150K, 160K, 0.25um TSMC, 200K and X-fab wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

**Pre Change:**

Gold (Au) or Palladium coated copper wire (PdCu) bond wire

**Post Change:**

Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire or PdCu wire	CuPdAu wire
<b>Die attach material</b>	CRM-1064L or 2200D or 84-1LMISR4	CRM-1064L
<b>Molding compound material</b>	GE800 or G600V	GE800
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**

None

**Reason for Change:**

To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**  
June 1, 2016 (date code: 1622)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	January 2016				---->				May 2016				May 2016				
	01	02	03	04					18	19	20	21	22	23	24	25	26
WW																	
Initial PCN Issue Date		X															
Qual Report Availability											X						
Final PCN Issue Date											X						
Implementation Date													X				

**Markings to Distinguish Revised from Unrevised Devices:**  
Traceability code

**Revision History:**

**January 13, 2016:** Issued initial notification.

**May 25, 2016:** Issued final notification. Attached the qualification report. Updated the summary table for the Qual Report Availability and Final PCN issue date. Revised the estimated first ship date from April 20, 2016 to June 1, 2016. Updated the scope of change from selected products of the 0.25um TSMC wafer technology available in 28L SPDIP, 18L and 20L PDIP package at MMT assembly site to selected products of the 40K, 57K, 77K, 90K, 120K, 150K, 160K, 0.25um TSMC, 200K and X-fab wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-08OJZL283\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-08OJZL283\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-08OJZL283\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
CF745-04/P
CF775-04/SP
DSPIC33FJ06GS001-E/P
DSPIC33FJ06GS001-I/P
DSPIC33FJ06GS101A-E/P
DSPIC33FJ06GS101A-I/P
DSPIC33FJ06GS102A-E/SP
DSPIC33FJ06GS102A-I/SP
DSPIC33FJ06GS102-E/SP
DSPIC33FJ06GS102-I/SP
DSPIC33FJ06GS202A-E/SP
DSPIC33FJ06GS202A-I/SP
DSPIC33FJ06GS202-E/SP
DSPIC33FJ06GS202-I/SP
DSPIC33FJ09GS302-E/SP
DSPIC33FJ09GS302-I/SP
DSPIC33FJ128GP202-E/SP
DSPIC33FJ128GP202-I/SP
DSPIC33FJ128GP802-E/SP
DSPIC33FJ128GP802-I/SP
DSPIC33FJ128MC202-E/SP
DSPIC33FJ128MC202-I/SP
DSPIC33FJ128MC802-E/SP
DSPIC33FJ128MC802-I/SP
DSPIC33FJ12GP201-E/P
DSPIC33FJ12GP201-I/P
DSPIC33FJ12GP202-E/SP
DSPIC33FJ12GP202-I/SP
DSPIC33FJ12MC201-E/P
DSPIC33FJ12MC201-I/P
DSPIC33FJ12MC202-E/SP
DSPIC33FJ12MC202-I/SP
DSPIC33FJ16GP101-E/P
DSPIC33FJ16GP101-H/P
DSPIC33FJ16GP101-I/P
DSPIC33FJ16GP102-E/SP
DSPIC33FJ16GP102-H/SP
DSPIC33FJ16GP102-I/SP
DSPIC33FJ16GS402-50I/SP
DSPIC33FJ16GS402-E/SP
DSPIC33FJ16GS402-H/SP
DSPIC33FJ16GS402-I/SP
DSPIC33FJ16GS502-50I/SP
DSPIC33FJ16GS502-E/SP

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
DSPIC33FJ16GS502-H/SP
DSPIC33FJ16GS502-I/SP
DSPIC33FJ16MC101-E/P
DSPIC33FJ16MC101-H/P
DSPIC33FJ16MC101-I/P
DSPIC33FJ16MC102-E/SP
DSPIC33FJ16MC102-H/SP
DSPIC33FJ16MC102-I/SP
DSPIC33FJ32GP101-E/P
DSPIC33FJ32GP101-I/P
DSPIC33FJ32GP102-I/SP
DSPIC33FJ32GP202-E/SP
DSPIC33FJ32GP202-I/SP
DSPIC33FJ32GP302-E/SP
DSPIC33FJ32GP302-I/SP
DSPIC33FJ32MC101-E/P
DSPIC33FJ32MC101-I/P
DSPIC33FJ32MC102-I/SP
DSPIC33FJ32MC202-E/SP
DSPIC33FJ32MC202-I/SP
DSPIC33FJ32MC302-E/SP
DSPIC33FJ32MC302-I/SP
DSPIC33FJ64GP202-E/SP
DSPIC33FJ64GP202-I/SP
DSPIC33FJ64GP802-E/SP
DSPIC33FJ64GP802-I/SP
DSPIC33FJ64MC202-E/SP
DSPIC33FJ64MC202-I/SP
DSPIC33FJ64MC802-E/SP
DSPIC33FJ64MC802-I/SP
ENC28J60-I/SP
HA3089-I/SP
HB12-100D0S/12DB30
HCS370/P
HCS370-I/P
HCS512/P
HCS512-I/P
HI12-100D0S/12DI30
HS12-100D0/12DS15
HS12-100D0/12DS2F
HS12-100D0S/12DS30
MCP2030A-I/P
MCP2030-I/P
MCP2036-I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
MCP2050-330E/P
MCP2050-500E/P
MCP2120-I/P
MCP2140A-I/P
MCP2140-I/P
MCP2140-I/PRVB
MCP2150-I/P
MCP2150-I/PRVB
MCP2150-I/PRVC
MCP2155-I/P
MCP2155-I/PRVB
MCP2155-I/PRVC
MCP2221-I/P
MCP23008-E/P
MCP23009-E/P
MCP23016-I/SP
MCP23017-E/SP
MCP23018-E/SP
MCP23S08-E/P
MCP23S09-E/P
MCP23S17-E/SP
MCP23S18-E/SP
MCP25020-E/P
MCP25020-I/P
MCP25025-I/P
MCP25050-E/P
MCP25050-I/P
MCP25055-I/P
MCP2510-E/P
MCP2510-I/P
MCP2515-E/P
MCP2515-E/PRB2
MCP2515-E/PRB4
MCP2515-I/P
MCP2515-I/PRB2
MCP2515-I/PRB4
MCP3004-I/P
MCP3008-I/P
MCP3204-BI/P
MCP3204-CI/P
MCP3208-BI/P
MCP3208-CI/P
MCP3302-BI/P
MCP3302-CI/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
MCP3304-BI/P
MCP3304-CI/P
MCP42010-E/P
MCP42010-I/P
MCP42050-E/P
MCP42050-I/P
MCP42100-E/P
MCP42100-I/P
MCP4231-103E/P
MCP4231-104E/P
MCP4231-502E/P
MCP4231-503E/P
MCP4241-103E/P
MCP4241-104E/P
MCP4241-502E/P
MCP4241-503E/P
MCP4251-103E/P
MCP4251-104E/P
MCP4251-502E/P
MCP4251-503E/P
MCP4261-103E/P
MCP4261-104E/P
MCP4261-502E/P
MCP4261-503E/P
MCP4331-103E/P
MCP4331-104E/P
MCP4331-502E/P
MCP4331-503E/P
MCP4341-103E/P
MCP4341-104E/P
MCP4341-502E/P
MCP4341-503E/P
MCP4902-E/P
MCP4912-E/P
MCP4922-E/P
MCP6004-E/P
MCP6004-I/P
MCP6024-E/P
MCP6024-I/P
MCP6044-E/P
MCP6044-I/P
MCP604-E/P
MCP604-I/P
MCP609-I/P

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PCN_JAON-08OJZL283
CATALOG_PART_NBR
MCP6144-E/P
MCP6144-I/P
MCP619-I/P
MCP6234-E/P
MCP6244-E/P
MCP6274-E/P
MCP6284-E/P
MCP6294-E/P
MCP6544-E/P
MCP6544-I/P
MCP6549-E/P
MCP6549-I/P
MCP6S26-I/P
MCP6S28-I/P
MCV14A-I/P
MCV18A-I/P
MCV28A-I/SP
PIC10F322-ICE/P
PIC12F675-ICD/P
PIC12F752-ICD/P
PIC12HV752-ICD/P
PIC14000-04/SP
PIC14000-04I/SP
PIC14000-20/SP
PIC14000-20I/SP
PIC16C505-04/P
PIC16C505-04E/P
PIC16C505-04I/P
PIC16C505-04I/P122
PIC16C505-20/P
PIC16C505-20E/P
PIC16C505-20I/P
PIC16C54-10/P
PIC16C54-10I/P
PIC16C54A-04/P
PIC16C54A-04/P070
PIC16C54A-04/P428
PIC16C54A-04E/P
PIC16C54A-04I/P
PIC16C54A-10/P
PIC16C54A-10I/P
PIC16C54A-20/P
PIC16C54A-20I/P
PIC16C54C-04/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16C54C-04/P053
PIC16C54C-04/P091
PIC16C54C-04/P103
PIC16C54C-04/P133
PIC16C54C-04/P148
PIC16C54C-04/P154
PIC16C54C-04E/P
PIC16C54C-04I/P
PIC16C54C-04I/P096
PIC16C54C-04I/P155
PIC16C54C-20/P
PIC16C54C-20E/P
PIC16C54C-20I/P
PIC16C54C-40/P
PIC16C54-HS/P
PIC16C54-HSE/P
PIC16C54-HSI/P
PIC16C54-LP/P
PIC16C54-LPE/P
PIC16C54-LPI/P
PIC16C54-RC/P
PIC16C54-RCE/P
PIC16C54-RCI/P
PIC16C54-RCI/P028
PIC16C54-RCI/P029
PIC16C54-XT/P
PIC16C54-XTI/P
PIC16C55-10/SP
PIC16C55-10I/SP
PIC16C554-04/P
PIC16C554-04I/P
PIC16C554-20/P
PIC16C554-20I/P
PIC16C558-04/P
PIC16C558-04E/P
PIC16C558-04I/P
PIC16C558-20/P
PIC16C558-20I/P
PIC16C55A-04/SP
PIC16C55A-04I/SP
PIC16C55A-20/SP
PIC16C55A-20I/SP
PIC16C55A-40/SP
PIC16C55-HS/SP



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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16C55-HSI/SP
PIC16C55-LP/SP
PIC16C55-LPI/SP
PIC16C55-RC/SP
PIC16C55-RCI/SP
PIC16C55-XT/SP
PIC16C55-XTE/SP
PIC16C55-XTI/SP
PIC16C56-10/P
PIC16C56-10I/P
PIC16C56A-04/P
PIC16C56A-04E/P
PIC16C56A-04I/P
PIC16C56A-20/P
PIC16C56A-20E/P
PIC16C56A-20I/P
PIC16C56A-40/P
PIC16C56-HS/P
PIC16C56-HSI/P
PIC16C56-LP/P
PIC16C56-LPE/P
PIC16C56-LPI/P
PIC16C56-RC/P
PIC16C56-RCI/P
PIC16C56-RCI/P045
PIC16C56-XT/P
PIC16C56-XTI/P
PIC16C57-10/SP
PIC16C57-10I/SP
PIC16C57C-04/SP
PIC16C57C-04E/SP
PIC16C57C-04I/SP
PIC16C57C-20/SP
PIC16C57C-20I/SP
PIC16C57C-40/SP
PIC16C57-HS/SP
PIC16C57-HSI/SP
PIC16C57-LP/SP
PIC16C57-LPI/SP
PIC16C57-RC/SP
PIC16C57-RCE/SP
PIC16C57-RCI/SP
PIC16C57-XT/SP
PIC16C57-XTE/SP

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16C57-XTI/SP
PIC16C58B-04/P
PIC16C58B-04E/P
PIC16C58B-04I/P
PIC16C58B-04I/P077
PIC16C58B-04I/P081
PIC16C58B-04I/P083
PIC16C58B-20/P
PIC16C58B-20E/P
PIC16C58B-20I/P
PIC16C58B-20I/P076
PIC16C58B-40/P
PIC16C620-04/P
PIC16C620-04E/P
PIC16C620-04I/P
PIC16C620-20/P
PIC16C620-20I/P
PIC16C620A-04/P
PIC16C620A-04E/P
PIC16C620A-04I/P
PIC16C620A-20/P
PIC16C620A-20I/P
PIC16C620A-40/P
PIC16C621-04/P
PIC16C621-04E/P
PIC16C621-04I/P
PIC16C621-20/P
PIC16C621-20E/P
PIC16C621-20I/P
PIC16C621A-04/P
PIC16C621A-04/P087
PIC16C621A-04E/P
PIC16C621A-04I/P
PIC16C621A-04I/P074
PIC16C621A-04I/P075
PIC16C621A-20/P
PIC16C621A-20I/P
PIC16C621A-40/P
PIC16C622-04/P
PIC16C622-04E/P
PIC16C622-04I/P
PIC16C622-20/P
PIC16C622-20I/P
PIC16C622A-04/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16C622A-04E/P
PIC16C622A-04I/P
PIC16C622A-04I/P4AP
PIC16C622A-20/P
PIC16C622A-20/PHXX
PIC16C622A-20E/P
PIC16C622A-20I/P
PIC16C622A-40/P
PIC16C62A-04/SP
PIC16C62A-04I/SP
PIC16C62A-10I/SP
PIC16C62A-20/SP
PIC16C62A-20I/SP
PIC16C62B-04/SP
PIC16C62B-04I/SP
PIC16C62B-20/SP
PIC16C62B-20/SPV01
PIC16C62B-20E/SP
PIC16C62B-20I/SP
PIC16C63-04/SP
PIC16C63-04I/SP
PIC16C63-10/SP
PIC16C63-10I/SP
PIC16C63-20/SP
PIC16C63-20I/SP
PIC16C63A-04/SP
PIC16C63A-04I/SP
PIC16C63A-20/SP
PIC16C63A-20E/SP
PIC16C63A-20I/SP
PIC16C642-04/SP
PIC16C642-04I/SP
PIC16C642-10I/SP
PIC16C642-20/SP
PIC16C642-20I/SP
PIC16C66-04/SP
PIC16C66-04I/SP
PIC16C66-10/SP
PIC16C66-10I/SP
PIC16C66-20/SP
PIC16C66-20E/SP
PIC16C66-20I/SP
PIC16C710-04/P
PIC16C710-04E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16C710-04I/P
PIC16C710-20/P
PIC16C710-20I/P
PIC16C71-04/P
PIC16C71-04I/P
PIC16C71-04I/P037
PIC16C711-04/P
PIC16C711-04/P054
PIC16C711-04E/P
PIC16C711-04I/P
PIC16C711-20/P
PIC16C711-20E/P
PIC16C711-20I/P
PIC16C71-20/P
PIC16C712-04/P
PIC16C712-04E/P
PIC16C712-04I/P
PIC16C71-20I/P
PIC16C712-20/P
PIC16C712-20E/P
PIC16C712-20I/P
PIC16C715-04/P
PIC16C715-04E/P
PIC16C715-04I/P
PIC16C715-20/P
PIC16C715-20E/P
PIC16C715-20I/P
PIC16C716-04/P
PIC16C716-04E/P
PIC16C716-04I/P
PIC16C716-20/P
PIC16C716-20I/P
PIC16C717/P
PIC16C717/P028
PIC16C717-I/P
PIC16C72-04/SP
PIC16C72-04I/SP
PIC16C72-10I/SP
PIC16C72-20/SP
PIC16C72-20E/SP
PIC16C72-20I/SP
PIC16C72A-04/SP
PIC16C72A-04E/SP
PIC16C72A-04I/SP

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16C72A-04I/SP4AP
PIC16C72A-20/SP
PIC16C72A-20I/SP
PIC16C73A-04/SP
PIC16C73A-04I/SP
PIC16C73A-10/SP
PIC16C73A-10I/SP
PIC16C73A-20/SP
PIC16C73A-20E/SP
PIC16C73A-20I/SP
PIC16C73B-04/SP
PIC16C73B-04E/SP
PIC16C73B-04I/SP
PIC16C73B-04I/SP4AP
PIC16C73B-20/SP
PIC16C73B-20E/SP
PIC16C73B-20I/SP
PIC16C745-I/SP
PIC16C745-I/SP025
PIC16C745-I/SPC02
PIC16C76-04/SP
PIC16C76-04E/SP
PIC16C76-04I/SP
PIC16C76-10/SP
PIC16C76-10I/SP
PIC16C76-20/SP
PIC16C76-20E/SP
PIC16C76-20I/SP
PIC16C770/P
PIC16C770/PHXX
PIC16C770-I/P
PIC16C771/P
PIC16C771-E/P
PIC16C771-I/P
PIC16C773/SP
PIC16C773-E/SP
PIC16C773-I/SP
PIC16C781-I/P
PIC16C782-I/P
PIC16CR54C-04/P081
PIC16CR54C-04/P108
PIC16CR58B-04I/P044
PIC16CR58B-04I/P075
PIC16CR58B-04I/P076

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16CR63-04I/SP075
PIC16CR63-04I/SP079
PIC16CR63-04I/SP082
PIC16CR63-04I/SP083
PIC16CR63-04I/SP084
PIC16CR63-04I/SP085
PIC16F1454-E/P
PIC16F1454-I/P
PIC16F1455-E/P
PIC16F1455-I/P
PIC16F1459-E/P
PIC16F1459-I/P
PIC16F1503-E/P
PIC16F1503-I/P
PIC16F1507-E/P
PIC16F1507-I/P
PIC16F1508-E/P
PIC16F1508-I/P
PIC16F1509-E/P
PIC16F1509-I/P
PIC16F1509-ICE/SP
PIC16F1512-E/SP
PIC16F1512-I/SP
PIC16F1513-E/SP
PIC16F1513-I/SP
PIC16F1516-E/SP
PIC16F1516-I/SP
PIC16F1518-E/SP
PIC16F1518-I/SP
PIC16F1574-E/P
PIC16F1574-I/P
PIC16F1575-E/P
PIC16F1575-I/P
PIC16F1578-E/P
PIC16F1578-I/P
PIC16F1579-E/P
PIC16F1579-I/P
PIC16F1613-E/P
PIC16F1613-I/P
PIC16F1614-E/P
PIC16F1614-I/P
PIC16F1615-E/P
PIC16F1615-I/P
PIC16F1618-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F1618-I/P
PIC16F1619-E/P
PIC16F1619-I/P
PIC16F1703-E/P
PIC16F1703-I/P
PIC16F1704-E/P
PIC16F1704-I/P
PIC16F1705-E/P
PIC16F1705-I/P
PIC16F1707-E/P
PIC16F1707-I/P
PIC16F1708-E/P
PIC16F1708-I/P
PIC16F1709-E/P
PIC16F1709-I/P
PIC16F1713-E/SP
PIC16F1713-I/SP
PIC16F1716-E/SP
PIC16F1716-I/SP
PIC16F1718-E/SP
PIC16F1718-I/SP
PIC16F1764-E/P
PIC16F1764-I/P
PIC16F1765-E/P
PIC16F1765-I/P
PIC16F1768-E/P
PIC16F1768-I/P
PIC16F1769-E/P
PIC16F1769-I/P
PIC16F1773-E/SP
PIC16F1773-I/SP
PIC16F1776-E/SP
PIC16F1776-I/SP
PIC16F1778-E/SP
PIC16F1778-I/SP
PIC16F1782-E/SP
PIC16F1782-I/SP
PIC16F1783-E/SP
PIC16F1783-I/SP
PIC16F1786-E/SP
PIC16F1786-I/SP
PIC16F1788-E/SP
PIC16F1788-I/SP
PIC16F1823-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F1823-I/P
PIC16F1824-E/P
PIC16F1824-I/P
PIC16F1825-E/P
PIC16F1825-I/P
PIC16F1825-I/P035
PIC16F1825-I/PC01
PIC16F1826-E/P
PIC16F1826-I/P
PIC16F1826-I/P025
PIC16F1826-I/P026
PIC16F1827-E/P
PIC16F1827-I/P
PIC16F1827-I/PC01
PIC16F1828-E/P
PIC16F1828-I/P
PIC16F1829-E/P
PIC16F1829-I/P
PIC16F1829-I/P024
PIC16F1829-I/PC01
PIC16F1829-ICE/SP
PIC16F1847-E/P
PIC16F1847-I/P
PIC16F1847-I/P020
PIC16F1847-I/PC01
PIC16F1847-ICE/SP
PIC16F1933-E/SP
PIC16F1933-I/SP
PIC16F1936-E/SP
PIC16F1936-I/SP
PIC16F1936-I/SP034
PIC16F1936-I/SP036
PIC16F1938-E/SP
PIC16F1938-I/SP
PIC16F505-E/P
PIC16F505-I/P
PIC16F505-I/P038
PIC16F505-I/P060
PIC16F505-ICD/P
PIC16F506-E/P
PIC16F506-I/P
PIC16F506-I/P045
PIC16F506-ICD/P
PIC16F526-E/P



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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F526-I/P
PIC16F526-ICD/P
PIC16F527-E/P
PIC16F527-I/P
PIC16F527-ICD/SP
PIC16F54-E/P
PIC16F54-I/P
PIC16F54-I/P022
PIC16F54-I/P024
PIC16F54-I/P026
PIC16F54-I/P031
PIC16F54-I/P035
PIC16F570-E/SP
PIC16F570-I/SP
PIC16F57-E/SP
PIC16F57-I/SP
PIC16F610-E/P
PIC16F610-I/P
PIC16F616-E/P
PIC16F616-I/P
PIC16F616-I/PC09
PIC16F627-04/P
PIC16F627-04I/P
PIC16F627-20/P
PIC16F627-20I/P
PIC16F627A-E/P
PIC16F627A-I/P
PIC16F627A-I/P035
PIC16F628-04/P
PIC16F628-04E/P
PIC16F628-04I/P
PIC16F628-04I/P043
PIC16F628-20/P
PIC16F628-20E/P
PIC16F628-20I/P
PIC16F628A-E/P
PIC16F628A-E/P079
PIC16F628A-I/P
PIC16F628A-I/P052
PIC16F628A-I/P058
PIC16F628A-I/P060
PIC16F628A-I/P069
PIC16F628A-I/P080
PIC16F630-C/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F630-E/P
PIC16F630-I/P
PIC16F630-I/P054
PIC16F631-E/P
PIC16F631-I/P
PIC16F636-E/P
PIC16F636-I/P
PIC16F648A-E/P
PIC16F648A-I/P
PIC16F648A-ICD/P
PIC16F676-C/P
PIC16F676-E/P
PIC16F676-I/P
PIC16F676-I/P055
PIC16F676-I/P056
PIC16F676-I/P057
PIC16F676-I/P059
PIC16F676-I/P060
PIC16F676-ICD/P
PIC16F677-E/P
PIC16F677-I/P
PIC16F677-I/P025
PIC16F684-E/P
PIC16F684-I/P
PIC16F685-E/P
PIC16F685-I/P
PIC16F687-E/P
PIC16F687-I/P
PIC16F688-E/P
PIC16F688-I/P
PIC16F689-E/P
PIC16F689-I/P
PIC16F690-E/P
PIC16F690-I/P
PIC16F716-E/P
PIC16F716-I/P
PIC16F716-I/P020
PIC16F716-I/P024
PIC16F716-I/P025
PIC16F716-I/P035
PIC16F716-I/P042
PIC16F716-I/P049
PIC16F716-I/P057
PIC16F716-I/P4AP

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F720-E/P
PIC16F720-I/P
PIC16F721-E/P
PIC16F721-I/P
PIC16F722A-E/SP
PIC16F722A-I/SP
PIC16F722-E/SP
PIC16F722-I/SP
PIC16F723A-E/SP
PIC16F723A-I/SP
PIC16F723-E/SP
PIC16F723-I/SP
PIC16F726-E/SP
PIC16F726-I/SP
PIC16F72-E/SP
PIC16F72-I/SP
PIC16F72-I/SP062
PIC16F72-I/SP063
PIC16F72-I/SP065
PIC16F72-I/SP080
PIC16F72-I/SP4AP
PIC16F72-I/SPC01
PIC16F737-E/SP
PIC16F737-I/SP
PIC16F73-E/SP
PIC16F73-I/SP
PIC16F73-I/SP127
PIC16F73-I/SP141
PIC16F73-I/SP159
PIC16F73-I/SP4AP
PIC16F73-I/SPD74
PIC16F753-E/P
PIC16F753-I/P
PIC16F753-ICD/P
PIC16F767-I/SP
PIC16F76-E/SP
PIC16F76-I/SP
PIC16F785-E/P
PIC16F785-I/P
PIC16F818-E/P
PIC16F818-I/P
PIC16F818-I/PTSL
PIC16F819-E/P
PIC16F819-I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F819-I/P026
PIC16F819-I/PTSL
PIC16F819-I/PV06
PIC16F83-04/P
PIC16F83-10/P
PIC16F84-04/P
PIC16F84-04I/P
PIC16F84-10/P
PIC16F84-10I/P
PIC16F84A-04/P
PIC16F84A-04E/P
PIC16F84A-04I/P
PIC16F84A-20/P
PIC16F84A-20E/P
PIC16F84A-20I/P
PIC16F870-E/SP
PIC16F870-I/SP
PIC16F872-E/SP
PIC16F872-I/SP
PIC16F873-04/SP
PIC16F873-04I/SP
PIC16F873-10E/SP
PIC16F873-20/SP
PIC16F873-20I/SP
PIC16F873A-E/SP
PIC16F873A-I/SP
PIC16F876-04/SP
PIC16F876-04E/SP
PIC16F876-04I/SP
PIC16F876-10E/SP
PIC16F876-20/SP
PIC16F876-20I/SP
PIC16F876A-E/SP
PIC16F876A-I/SP
PIC16F87-E/P
PIC16F87-I/P
PIC16F882-E/SP
PIC16F882-I/SP
PIC16F883-E/SP
PIC16F883-I/SP
PIC16F883-I/SP029
PIC16F883-I/SP030
PIC16F883-I/SP033
PIC16F883-I/SP034

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16F883-I/SP036
PIC16F883-I/SP048
PIC16F883-I/SP049
PIC16F883-I/SP051
PIC16F883-I/SP052
PIC16F883-I/SP053
PIC16F883-I/SP056
PIC16F883-I/SP057
PIC16F883-I/SP058
PIC16F883-I/SP059
PIC16F883-I/SP066
PIC16F883-I/SP067
PIC16F883-I/SP068
PIC16F883-I/SP069
PIC16F886-E/SP
PIC16F886-I/SP
PIC16F886-I/SP027
PIC16F886-I/SP050
PIC16F886-I/SP051
PIC16F88-E/P
PIC16F88-I/P
PIC16F88-I/P043
PIC16F913-E/SP
PIC16F913-I/SP
PIC16F913-I/SP021
PIC16F913-I/SP029
PIC16F913-I/SP030
PIC16F916-E/SP
PIC16F916-I/SP
PIC16HV610-E/P
PIC16HV610-I/P
PIC16HV616-E/P
PIC16HV616-I/P
PIC16HV616-I/P021
PIC16HV753-E/P
PIC16HV753-I/P
PIC16HV785-E/P
PIC16HV785-I/P
PIC16LC505-04/P
PIC16LC505-04I/P
PIC16LC54A-04/P
PIC16LC54A-04I/P
PIC16LC54C-04/P
PIC16LC54C-04I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16LC554-04/P
PIC16LC554-04I/P
PIC16LC558-04/P
PIC16LC558-04I/P
PIC16LC55A-04/SP
PIC16LC55A-04I/SP
PIC16LC56A-04/P
PIC16LC56A-04I/P
PIC16LC57C-04/SP
PIC16LC57C-04I/SP
PIC16LC58B-04/P
PIC16LC58B-04I/P
PIC16LC620-04/P
PIC16LC620-04I/P
PIC16LC620A-04/P
PIC16LC620A-04E/P
PIC16LC620A-04I/P
PIC16LC621-04/P
PIC16LC621-04I/P
PIC16LC621A-04/P
PIC16LC621A-04I/P
PIC16LC622-04/P
PIC16LC622-04I/P
PIC16LC622A-04/P
PIC16LC622A-04I/P
PIC16LC62A-04/SP
PIC16LC62B-04/SP
PIC16LC62B-04I/SP
PIC16LC63-04I/SP
PIC16LC63A-04/SP
PIC16LC63A-04I/SP
PIC16LC642-04/SP
PIC16LC66-04I/SP
PIC16LC710-04/P
PIC16LC710-04I/P
PIC16LC71-04/P
PIC16LC71-04I/P
PIC16LC711-04/P
PIC16LC711-04E/P
PIC16LC711-04I/P
PIC16LC712-04/P
PIC16LC712-04I/P
PIC16LC715-04/P
PIC16LC715-04I/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16LC716-04/P
PIC16LC716-04I/P
PIC16LC717/P
PIC16LC717-I/P
PIC16LC72-04/SP
PIC16LC72-04I/SP
PIC16LC72A-04/SP
PIC16LC72A-04I/SP
PIC16LC73A-04/SP
PIC16LC73A-04I/SP
PIC16LC73B-04/SP
PIC16LC73B-04I/SP
PIC16LC76-04/SP
PIC16LC76-04I/SP
PIC16LC770/P
PIC16LC770-I/P
PIC16LC771/P
PIC16LC771-I/P
PIC16LC773-I/SP
PIC16LC781-I/P
PIC16LC782-I/P
PIC16LF1454-E/P
PIC16LF1454-I/P
PIC16LF1455-E/P
PIC16LF1455-I/P
PIC16LF1459-E/P
PIC16LF1459-I/P
PIC16LF1503-E/P
PIC16LF1503-I/P
PIC16LF1507-E/P
PIC16LF1507-I/P
PIC16LF1508-E/P
PIC16LF1508-I/P
PIC16LF1509-E/P
PIC16LF1509-I/P
PIC16LF1509-ICE/SP
PIC16LF1512-E/SP
PIC16LF1512-I/SP
PIC16LF1513-E/SP
PIC16LF1513-I/SP
PIC16LF1516-E/SP
PIC16LF1516-I/SP
PIC16LF1518-E/SP
PIC16LF1518-I/SP

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16LF1554-E/P
PIC16LF1554-I/P
PIC16LF1559-E/P
PIC16LF1559-I/P
PIC16LF1566-E/SP
PIC16LF1566-I/SP
PIC16LF1574-E/P
PIC16LF1574-I/P
PIC16LF1575-E/P
PIC16LF1575-I/P
PIC16LF1578-E/P
PIC16LF1578-I/P
PIC16LF1579-E/P
PIC16LF1579-I/P
PIC16LF1613-E/P
PIC16LF1613-I/P
PIC16LF1614-E/P
PIC16LF1614-I/P
PIC16LF1615-E/P
PIC16LF1615-I/P
PIC16LF1618-E/P
PIC16LF1618-I/P
PIC16LF1619-E/P
PIC16LF1619-I/P
PIC16LF1703-E/P
PIC16LF1703-I/P
PIC16LF1704-E/P
PIC16LF1704-I/P
PIC16LF1705-E/P
PIC16LF1705-I/P
PIC16LF1707-E/P
PIC16LF1707-I/P
PIC16LF1708-E/P
PIC16LF1708-I/P
PIC16LF1709-E/P
PIC16LF1709-I/P
PIC16LF1713-E/SP
PIC16LF1713-I/SP
PIC16LF1716-E/SP
PIC16LF1716-I/SP
PIC16LF1718-E/SP
PIC16LF1718-I/SP
PIC16LF1764-E/P
PIC16LF1764-I/P



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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16LF1765-E/P
PIC16LF1765-I/P
PIC16LF1768-E/P
PIC16LF1768-I/P
PIC16LF1769-E/P
PIC16LF1769-I/P
PIC16LF1773-E/SP
PIC16LF1773-I/SP
PIC16LF1776-E/SP
PIC16LF1776-I/SP
PIC16LF1778-E/SP
PIC16LF1778-I/SP
PIC16LF1782-E/SP
PIC16LF1782-I/SP
PIC16LF1783-E/SP
PIC16LF1783-I/SP
PIC16LF1786-E/SP
PIC16LF1786-I/SP
PIC16LF1788-E/SP
PIC16LF1788-I/SP
PIC16LF1823-E/P
PIC16LF1823-I/P
PIC16LF1824-E/P
PIC16LF1824-I/P
PIC16LF1825-E/P
PIC16LF1825-I/P
PIC16LF1826-E/P
PIC16LF1826-I/P
PIC16LF1827-E/P
PIC16LF1827-I/P
PIC16LF1828-E/P
PIC16LF1828-I/P
PIC16LF1829-E/P
PIC16LF1829-I/P
PIC16LF1829-ICE/SP
PIC16LF1847-E/P
PIC16LF1847-I/P
PIC16LF1847-ICE/SP
PIC16LF1902-E/SP
PIC16LF1902-I/SP
PIC16LF1903-E/SP
PIC16LF1903-I/SP
PIC16LF1906-E/SP
PIC16LF1906-I/SP

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Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16LF1933-E/SP
PIC16LF1933-I/SP
PIC16LF1936-E/SP
PIC16LF1936-I/SP
PIC16LF1938-E/SP
PIC16LF1938-I/SP
PIC16LF627-04/P
PIC16LF627-04I/P
PIC16LF627A-I/P
PIC16LF628-04/P
PIC16LF628-04I/P
PIC16LF628A-I/P
PIC16LF648A-I/P
PIC16LF720-E/P
PIC16LF720-I/P
PIC16LF721-E/P
PIC16LF721-I/P
PIC16LF722A-E/SP
PIC16LF722A-I/SP
PIC16LF722-E/SP
PIC16LF722-I/SP
PIC16LF723A-E/SP
PIC16LF723A-I/SP
PIC16LF723-E/SP
PIC16LF723-I/SP
PIC16LF726-E/SP
PIC16LF726-I/SP
PIC16LF72-I/SP
PIC16LF737-I/SP
PIC16LF73-I/SP
PIC16LF767-I/SP
PIC16LF76-I/SP
PIC16LF818-I/P
PIC16LF819-I/P
PIC16LF819-I/PTSL
PIC16LF83-04I/P
PIC16LF84-04/P
PIC16LF84-04I/P
PIC16LF84A-04/P
PIC16LF84A-04I/P
PIC16LF870-I/SP
PIC16LF872-I/SP
PIC16LF873-04/SP
PIC16LF873-04I/SP

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC16LF873A-I/SP
PIC16LF876-04/SP
PIC16LF876-04I/SP
PIC16LF876A-I/SP
PIC16LF87-I/P
PIC16LF88-I/P
PIC16LV54A-02/P
PIC16LV54A-02I/P
PIC18C242-E/SP
PIC18C242-I/SP
PIC18C252-I/SP
PIC18F1220-E/P
PIC18F1220-H/P
PIC18F1220-I/P
PIC18F1230-E/P
PIC18F1230-I/P
PIC18F1230-I/PXXX
PIC18F1320-E/P
PIC18F1320-H/P
PIC18F1320-I/P
PIC18F1330-E/P
PIC18F1330-I/P
PIC18F1330-I/PXXX
PIC18F13K22-E/P
PIC18F13K22-I/P
PIC18F13K50-E/P
PIC18F13K50-I/P
PIC18F14K22-E/P
PIC18F14K22-I/P
PIC18F14K50-E/P
PIC18F14K50-I/P
PIC18F2220-E/SP
PIC18F2220-I/SP
PIC18F2221-E/SP
PIC18F2221-I/SP
PIC18F2320-E/SP
PIC18F2320-I/SP
PIC18F2321-E/SP
PIC18F2321-I/SP
PIC18F2331-E/SP
PIC18F2331-I/SP
PIC18F23K20-E/SP
PIC18F23K20-I/SP
PIC18F23K22-E/SP

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC18F23K22-I/SP
PIC18F2410-E/SP
PIC18F2410-I/SP
PIC18F2420-E/SP
PIC18F2420-I/SP
PIC18F2423-E/SP
PIC18F2423-I/SP
PIC18F242-E/SP
PIC18F242-I/SP
PIC18F2431-E/SP
PIC18F2431-I/SP
PIC18F2439-I/SP
PIC18F2450-I/SP
PIC18F2455-I/SP
PIC18F2458-I/SP
PIC18F2480-E/SP
PIC18F2480-I/SP
PIC18F248-E/SP
PIC18F248-I/SP
PIC18F24J10-I/SP
PIC18F24J11-I/SP
PIC18F24J50-I/SP
PIC18F24K20-E/SP
PIC18F24K20-I/SP
PIC18F24K22-E/SP
PIC18F24K22-I/SP
PIC18F24K50-E/SP
PIC18F24K50-I/SP
PIC18F2510-E/SP
PIC18F2510-I/SP
PIC18F2515-I/SP
PIC18F2520-E/SP
PIC18F2520-I/SP
PIC18F2523-E/SP
PIC18F2523-I/SP
PIC18F2525-E/SP
PIC18F2525-I/SP
PIC18F2525-I/SP026
PIC18F2525-I/SP027
PIC18F252-E/SP
PIC18F252-I/SP
PIC18F2539-I/SP
PIC18F2550-I/SP
PIC18F2553-I/SP

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC18F2580-E/SP
PIC18F2580-I/SP
PIC18F2585-E/SP
PIC18F2585-H/SP
PIC18F2585-I/SP
PIC18F258-E/SP
PIC18F258-I/SP
PIC18F25J10-I/SP
PIC18F25J11-I/SP
PIC18F25J50-I/SP
PIC18F25K20-E/SP
PIC18F25K20-I/SP
PIC18F25K22-E/SP
PIC18F25K22-I/SP
PIC18F25K50-E/SP
PIC18F25K50-I/SP
PIC18F25K80-E/SP
PIC18F25K80-I/SP
PIC18F2610-E/SP
PIC18F2610-I/SP
PIC18F2620-E/SP
PIC18F2620-I/SP
PIC18F2620-I/SPC03
PIC18F2680-E/SP
PIC18F2680-H/SP
PIC18F2680-I/SP
PIC18F2682-E/SP
PIC18F2682-I/SP
PIC18F2685-E/SP
PIC18F2685-I/SP
PIC18F26J11-I/SP
PIC18F26J13-I/SP
PIC18F26J50-I/SP
PIC18F26J53-I/SP
PIC18F26K20-E/SP
PIC18F26K20-I/SP
PIC18F26K22-E/SP
PIC18F26K22-I/SP
PIC18F26K80-E/SP
PIC18F26K80-I/SP
PIC18F27J13-I/SP
PIC18F27J53-I/SP
PIC18LC252-I/SP
PIC18LF1220-I/P

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC18LF1230-I/P
PIC18LF1320-I/P
PIC18LF1330-I/P
PIC18LF13K22-E/P
PIC18LF13K22-I/P
PIC18LF13K50-I/P
PIC18LF14K22-E/P
PIC18LF14K22-I/P
PIC18LF14K50-I/P
PIC18LF2220-I/SP
PIC18LF2221-I/SP
PIC18LF2320-I/SP
PIC18LF2321-I/SP
PIC18LF2331-I/SP
PIC18LF23K22-E/SP
PIC18LF23K22-I/SP
PIC18LF2410-I/SP
PIC18LF2420-I/SP
PIC18LF2423-I/SP
PIC18LF242-I/SP
PIC18LF2431-I/SP
PIC18LF2450-I/SP
PIC18LF2455-I/SP
PIC18LF2458-I/SP
PIC18LF2480-I/SP
PIC18LF248-I/SP
PIC18LF24J10-I/SP
PIC18LF24J11-I/SP
PIC18LF24J50-I/SP
PIC18LF24K22-E/SP
PIC18LF24K22-I/SP
PIC18LF24K50-E/SP
PIC18LF24K50-I/SP
PIC18LF2510-I/SP
PIC18LF2515-I/SP
PIC18LF2520-I/SP
PIC18LF2523-I/SP
PIC18LF2525-I/SP
PIC18LF252-I/SP
PIC18LF2539-I/SP
PIC18LF2550-I/SP
PIC18LF2553-I/SP
PIC18LF2580-I/SP
PIC18LF2585-I/SP

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC18LF258-I/SP
PIC18LF25J10-I/SP
PIC18LF25J11-I/SP
PIC18LF25J50-I/SP
PIC18LF25K22-E/SP
PIC18LF25K22-I/SP
PIC18LF25K50-E/SP
PIC18LF25K50-I/SP
PIC18LF25K80-I/SP
PIC18LF2610-I/SP
PIC18LF2620-I/SP
PIC18LF2680-I/SP
PIC18LF2682-I/SP
PIC18LF2685-I/SP
PIC18LF26J11-I/SP
PIC18LF26J13-I/SP
PIC18LF26J50-I/SP
PIC18LF26J53-I/SP
PIC18LF26K22-E/SP
PIC18LF26K22-I/SP
PIC18LF26K80-I/SP
PIC18LF27J13-I/SP
PIC18LF27J53-I/SP
PIC24F04KA200-I/P
PIC24F04KA201-I/P
PIC24F04KL100-E/P
PIC24F04KL100-I/P
PIC24F04KL101-E/P
PIC24F04KL101-I/P
PIC24F08KA101-E/P
PIC24F08KA101-I/P
PIC24F08KA102-E/SP
PIC24F08KA102-I/SP
PIC24F08KL200-E/P
PIC24F08KL200-I/P
PIC24F08KL201-E/P
PIC24F08KL201-I/P
PIC24F08KL301-E/P
PIC24F08KL301-I/P
PIC24F08KL302-E/SP
PIC24F08KL302-I/SP
PIC24F08KL401-E/P
PIC24F08KL401-I/P
PIC24F08KL402-E/SP

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC24F08KL402-I/SP
PIC24F08KM101-E/P
PIC24F08KM101-I/P
PIC24F08KM102-E/SP
PIC24F08KM102-I/SP
PIC24F08KM202-E/SP
PIC24F08KM202-I/SP
PIC24F16KA101-E/P
PIC24F16KA101-I/P
PIC24F16KA102-E/SP
PIC24F16KA102-I/SP
PIC24F16KA301-E/P
PIC24F16KA301-I/P
PIC24F16KA302-E/SP
PIC24F16KA302-I/SP
PIC24F16KL401-E/P
PIC24F16KL401-I/P
PIC24F16KL402-E/SP
PIC24F16KL402-I/SP
PIC24F16KM102-E/SP
PIC24F16KM102-I/SP
PIC24F16KM202-E/SP
PIC24F16KM202-I/SP
PIC24F32KA301-E/P
PIC24F32KA301-I/P
PIC24F32KA302-E/SP
PIC24F32KA302-I/SP
PIC24FJ16GA002-E/SP
PIC24FJ16GA002-I/SP
PIC24FJ16MC102-E/SP
PIC24FJ16MC102-H/SP
PIC24FJ16MC102-I/SP
PIC24FJ32GA002-E/SP
PIC24FJ32GA002-I/SP
PIC24FJ32GA102-I/SP
PIC24FJ32GB002-I/SP
PIC24FJ32MC102-I/SP
PIC24FJ48GA002-I/SP
PIC24FJ64GA002-E/SP
PIC24FJ64GA002-I/SP
PIC24FJ64GA102-I/SP
PIC24FJ64GB002-I/SP
PIC24FV08KM101-E/P
PIC24FV08KM101-I/P



JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
PIC24FV08KM102-E/SP
PIC24FV08KM102-I/SP
PIC24FV08KM202-E/SP
PIC24FV08KM202-I/SP
PIC24FV16KA301-I/P
PIC24FV16KA302-E/SP
PIC24FV16KA302-I/SP
PIC24FV16KM102-E/SP
PIC24FV16KM102-I/SP
PIC24FV16KM202-E/SP
PIC24FV16KM202-I/SP
PIC24FV32KA302-E/SP
PIC24FV32KA302-I/SP
PIC24HJ128GP202-E/SP
PIC24HJ128GP202-I/SP
PIC24HJ128GP502-E/SP
PIC24HJ128GP502-I/SP
PIC24HJ12GP201-E/P
PIC24HJ12GP201-I/P
PIC24HJ12GP202-E/SP
PIC24HJ12GP202-I/SP
PIC24HJ32GP202-E/SP
PIC24HJ32GP202-I/SP
PIC24HJ32GP302-E/SP
PIC24HJ32GP302-I/SP
PIC24HJ64GP202-E/SP
PIC24HJ64GP202-I/SP
PIC24HJ64GP502-E/SP
PIC24HJ64GP502-I/SP
RE266E16F
RE267E16F
RE272E18F
RE273E16F
RE274E18F
RE275E16F
RE276E18F
RE277E16F
RE278E18F
RE279E16F
RE288E16F
RE296E16F
RE297E16F
RE298E16F
RE299E16F

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
RE302E16F
RE310E16F
RE320E16F
RE321E16F
RE342E16F
RE46C104E14F
RE46C105E14F
RE46C107E16F
RE46C109E16F
RE46C119E16F
RE46C120E16F
RE46C121E16F
RE46C122E16F
RE46C126E16F
RE46C127E16F
RE46C129E16F
RE46C140E16F
RE46C140E16F-AAA
RE46C141E16F
RE46C143E16F
RE46C144E16F
RE46C144E16F-AAB
RE46C144V10E16F
RE46C145E16F
RE46C152E16F
RE46C162E16F
RE46C163E16F
RE46C165E16F
RE46C166E16F
RE46C167E16F
RE46C168E16F
RE46C180E16F
RE46C200E14F
TC4467CPD
TC4467EPD
TC4468CPD
TC4468EPD
TC4469CPD
TC4469EPD
TC514CPJ
TC520ACPD
TC7650CPD
TC7652CPD
TC9400CPD

JAON-08OJZL283 - CCB 1834 Final Notice: Qualification of CuPdAu bond wire in selected products of different wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-08OJZL283
CATALOG_PART_NBR
TC9401CPD
TC9402CPD



**MICROCHIP**

**QUALIFICATION REPORT**  
RELIABILITY LABORATORY

**PCN #: JAON-08OJZL283**

**Date**  
**March 22, 2016**

**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L SPDIP package at MMT assembly site. The selected products of the 40K, 57K, 77K, 90K, 120K, 150K, 160K, 200K and X-fab wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site will qualify by similarity.**

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## **MICROCHIP**

### **PACKAGE QUALIFICATION REPORT**

**Purpose** Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L SPDIP package at MMT assembly site. The selected products of the 40K, 57K, 77K, 90K, 120K, 150K, 160K, 200K and X-fab wafer technologies available in 28L SPDIP, 14L, 16L, 18L and 20L PDIP packages at MMT assembly site will qualify by similarity.

**CN** BC160306  
**QUAL ID** Q16046  
**MP CODE** YGAQ14M3XCAA  
**Part No.** DSPIC33FJ12MC202-E/SP  
**Bonding No.** BDM-000977 Rev. A  
**CCB No.** 1834

#### **Package**

**Type** 28L SPDIP  
**Package size** 300 mils  
**Die thickness** 15 mils  
**Die size** 135.3 x 123.9 mils

#### **Lead Frame**

**Paddle size** 180 x 240 mils  
**Material** CDA194  
**Surface** Ag Spot Plated  
**Process** Stamped  
**Lead Lock** No  
**Part Number** 10102822  
**Treatment** None

#### **Die attach material**

**Epoxy** CRM-1064L  
**Wire** CuPdAu wire  
**Mold Compound** GE800  
**Plating Composition** Matte Tin



## MICROCHIP PACKAGE QUALIFICATION REPORT

### Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-164300361.000	TC03916178582.D00	1603PBH
MMT-164300745.000	TC03916178582.D00	1603SUE
MMT-164300864.000	TC03916178582.D00	1603TYP

**Result**       Pass       Fail       \_\_\_\_\_

28L SPDIP (.300") assembled by MMT (ALPH) pass reliability test per QCI-39000.

**Prepared By:** Thinnapol **Date:** March 22, 2016 (Sr. Reliability Engineer)

(Mr. Thinnapol Nakkasun)

**Approved By:** Som **Date:** March 22, 2016 (Reliability Manager)

(Mr. Somnuek Thongprasert)

## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>Electrical Test</b>	<b>Electrical Test:</b> +25 °C,85 °C and 125 °C System: J750	JESD22- A113	693(0)	693		Good Devices
<b>Temp Cycle</b>	<b>Stress Condition:</b> (Standard) 65 °C to +150 °C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22- A104		231		
	<b>Electrical Test:</b> + 85 °C and 125 °C System: J750		231(0)	0/231	Pass	77 units / lot
	<b>Bond Strength:</b> Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
<b>UNBIASED-HAST</b>	<b>Stress Condition:</b> (Standard) +130 °C/85%RH, 96 hrs. System: HAST 6000X	JESD22- A118		231		
	<b>Electrical Test:</b> +25 °C System: J750		231(0)	0/231	Pass	77 units / lot

## PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>HAST</b>	<b>Stress Condition:</b> (Standard) +130°C/85%RH, 96 hrs. <b>Bias Volt:</b> 3.6 Volts System: HAST 6000X  <b>Electrical Test:</b> +25°C,85°C and 125°C System: J750	JESD22- A110	231(0)	231  0/231	Pass	77 units / lot
<b>High Temperature Storage Life</b>	<b>Stress Condition:</b> Bake 175°C, 504 hrs System: SHEL LAB  <b>Electrical Test:</b> + 25°C,85°C and 125°C System: J750	JESD22 -A103	45(0)	45  0/45	Pass	45 units
<b>Bond Strength</b>	Wire Pull (> 2.5 grams)	JESD22 -B116	30 (0) Wires	0/30	Pass	
<b>Data Assembly</b>	Bond Shear (>15.00 grams)		30 (0) bonds	0/30	Pass	